

METHOD AND APPARATUS FOR ATTACHING A PEELING TAPE

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ABSTRACT OF THE DISCLOSURE

10 In a peeling tape attaching method for attaching a
peeling tape (4) on a surface protective film (11)
attached on the surface of a wafer (20), the wafer is
supported on a movable table (31) with the surface
protective film up and the peeling tape is supplied on
the surface protective film of the wafer. The movable
table is moved in such a manner that an end (28) of the
15 wafer is located under a peeling tape attaching unit
(46), and pressure is exerted by pressing the peeling
tape attaching unit against the surface protective film
of the wafer via the peeling tape. After that, the
movable table is moved toward the other end (29) of the
20 wafer, and upon movement of the movable table, by a
predetermined distance, from the peeling tape attaching
unit, the pressure is canceled. As a result, the wafer
is prevented from cracking at the time of attaching the
peeling tape. Further, a peeling tape attaching
25 apparatus for carrying out this method is provided.

Fig. 2